

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Jae-Hyuk CHANG	08/08/2008
Kyu-Young KIM	08/08/2008
RECEIVING PARTY DATA	
Name:	Samsung Electronics Co., Ltd.
Street Address:	416 Maetan-dong, Yeongtong-gu, Gyeonggi-do
City:	Suwon-si
State/Country:	KOREA, REPUBLIC OF
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	12324231
CORRESPONDENCE DATA	
Fax Number:	(703)288-5139
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
Phone:	703-288-5105
Email:	patent@park-law.com
Correspondent Name:	H.C. Park & Associates, PLC
Address Line 1:	8500 Leesburg Pike, Suite 7500
Address Line 4:	Vienna, VIRGINIA 22182
ATTORNEY DOCKET NUMBER:	P2392US00
NAME OF SUBMITTER:	Hae-Chan Park
Total Attachments: 2 source=P2392US00 Assignment filed with USPTO#page1.tif source=P2392US00 Assignment filed with USPTO#page2.tif	

OP \$40.00 12324231



ASSIGNMENT

Whereas, Assignor has invented certain new and useful processes, machines, articles of manufacture, compositions of matter, and/or improvements thereof ("Invention") disclosed in

an application for United States Letters Patent entitled **METHOD OF MANUFACTURING THIN FILM TRANSISTOR SUBSTRATE** ("Application");

upon which United States Letters Patent, Patent Number _____, has issued ("Patent");

Whereas, Assignor desires to convey all rights, titles, and interests in and to the same to:

Samsung Electronics Co., Ltd.
416 Maetan-dong, Yeongtong-gu
Gyeonggi-do
Suwon-si
South Korea

Samsung Electronics Co., Ltd. herein further referred to as ("Assignee").

Now, for valuable consideration by Assignee to Assignor, the receipt of which is hereby acknowledged, and for other good and valuable consideration, Assignee and Assignor hereby agree as follows:

Assignor hereby conveys, assigns, sells and transfers to Assignee all rights, title and interests in and to the Invention disclosed in said application and in and to any Letters Patent of the United States (US), any continuation, division, renewal, or substitute thereof, and hereby grant to Assignee the right to apply in its own name for patents or Inventor's certificates and related rights heretofore or hereafter filed for the Invention in any and all countries, including (without limitation) all rights to claim priority based thereon, all patents granted thereon and all reissues, extensions and renewals thereof.

Assignor hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this Assignment.

Assignor further covenants that Assignee will, upon Assignee's request, be provided promptly with all pertinent facts and documents relating to the Invention, Patent, Application and any patents granted thereon, as may be known and accessible to Assignor, and Assignor will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to Assignee or Assignee's legal representative any and all papers, instruments or affidavits required to apply for, protect, obtain, maintain, issue, defend and enforce the Application, Patent, Invention, whether in the US or any and all foreign countries and any patents granted thereon and/or for obtaining any reissue or reissues of any patent which may be granted for the invention and perform such further acts which may be necessary



or desirable to carry out the intent of this agreement as the Assignee thereof shall hereafter require and prepare at assignee's expense.

IN WITNESS WHEREOF, Assignor has hereunto set hand and seal.

First Inventor's Name: Jae-Hyuk CHANG

Address: 306-702, Hansolmaeul Hanil apt.
Jeongja-dong, Bundang-gu, Gyeonggi-do
Seongnam-si
South Korea

First Inventor's Signature: Chang, Jaehyuk

Date: 2008. 6. 8

Second Inventor's Name: Kyu-Young KIM

Address: 634-703 Sinnamusil 6-danji Sinmyeong Apt.,
Yeongtong-dong, Yeongtong-gu, Gyeonggi-do
Suwon-si
South Korea

Second Inventor's Signature: [Signature]

Date: 2008. 8. 8